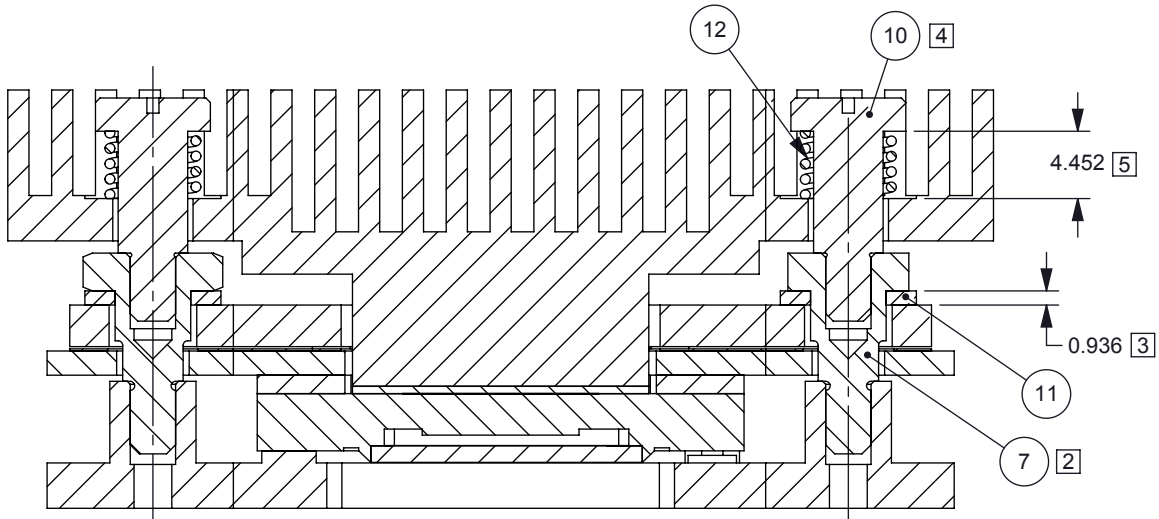
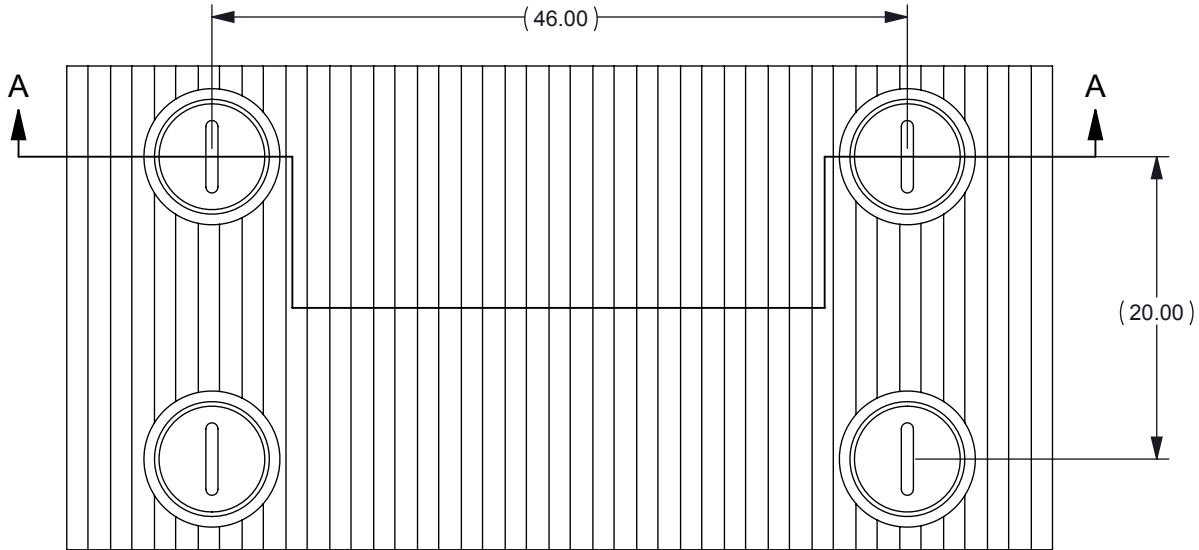
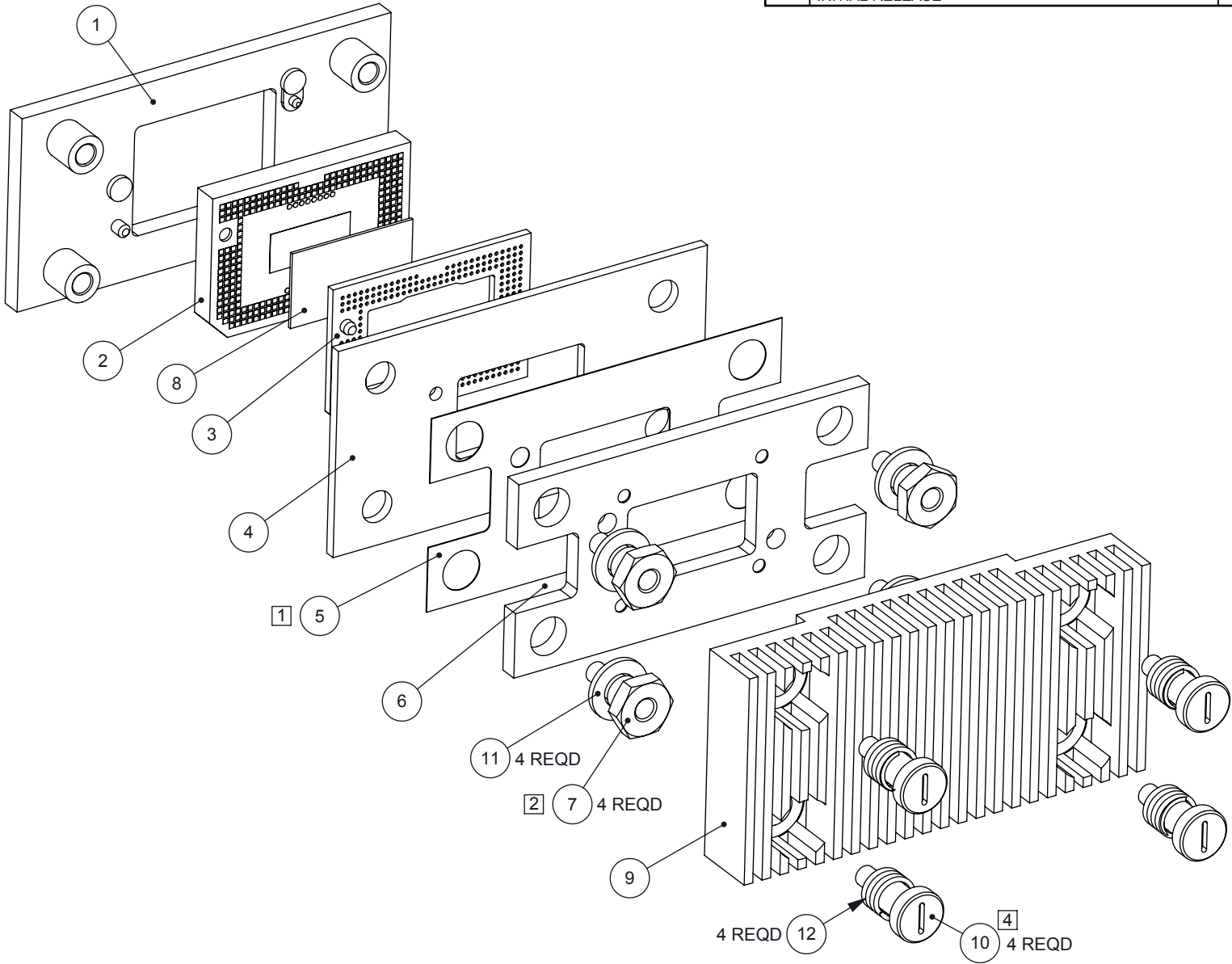



NOTES: UNLESS OTHERWISE SPECIFIED:

- [1] THE INSULATOR (ITEM 5) NEEDS TO BE OF SUFFICIENT THICKNESS TO ISOLATE THE PCB FROM THE METAL CLAMP (ITEM 6), TO KEEP IT FROM CAPACITIVELY COUPLING SIGNALS TOGETHER.
- [2] WHEN TIGHTENING STANDOFFS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOAD FOR THE ELECTRICAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE STANDOFFS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.
- [3] CRITICAL GAP FOR COMPRESSION WASHER DESIGN TO CONTROL LOADS ON THE DMD ELECTRICAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES. THE RESULTING FORCE APPLIED BY THE COMPRESSION WASHER DEPENDS ON GAP SIZE AND WASHER MATERIAL PROPERTIES.
- [4] WHEN TIGHTENING SCREWS (ITEM 10) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.
- [5] CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.



SECTION A-A

4	12	LEE SPRING LC 026CD 01S	COIL SPRING	
4	11	2515292	WASHER, COMPRESSION	
4	10	2515251	SCREW, SHOULDER, CONCEPT #1	
1	9	2525246	HEAT SINK SERIES 410 CONCEPT #1	
1	8	2515247	THERMAL PAD	
4	7	2515252	STANDOFF	
1	6	2515248	CLAMP, SERIES 410 PCB	
1	5	2515250	INSULATOR, PCB	
1	4	2515249	PCB, OUTLINE SERIES 410	
1	3	2515243	INTERPOSER, SERIES 410	
1	2		SERIES 410 DMD	
1	1	2515245	INTERFACE, SERIES 410	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

		UNLESS OTHERWISE SPECIFIED <ul style="list-style-type: none">● DIMENSIONS ARE IN MILLIMETERS● TOLERANCES: ANGLES ±1° 2 PLACE DECIMALS ±0.25 1 PLACE DECIMALS ±0.50● DIMENSIONAL LIMITS APPLY BEFORE PROCESSES● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994● REMOVE ALL BURRS AND SHARP EDGES● PARENTHETICAL INFO FOR REF ONLY	DWN J. McKINLEY	DATE 8/27/2016	 TEXAS INSTRUMENTS				
			Engr		ASSEMBLY, SERIES 410 DMD MOUNTING CONCEPT				
			CQE/QA						
			CM						
NONE	0314RD					SIZE B		DWG NO 2515244	REV A
NEXT ASSY	USED ON		Apprvd McKINLEY	8/29/2016	SCALE 2:1			SHEET 1 OF 2	
APPLICATION									

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SSZZ031 January 01, 2013



DWN	DATE
J. McKINLEY	8/27/2016

SIZE	B
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DRAWING NO	REV
2515244-Mounting-Concept1	

REV
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SCALE 2:1

SHEET 2 OF 2